

Title (en)

Electrical contact, method for assembly by welding a contact pad to a metal support in order to make said contact

Title (de)

Elektrischer Kontakt, Verbindungsverfahren durch Schweißen einer Kontaktplatte auf eine Metallhalterung zum Herstellen eines solchen Kontakts

Title (fr)

Contact électrique, procede d'assemblage par soudure d'une pastille de contact sur un support metallique pour realiser un tel contact.

Publication

**EP 2216795 B1 20150513 (FR)**

Application

**EP 10354005 A 20100129**

Priority

FR 0900517 A 20090206

Abstract (en)

[origin: EP2216795A1] The contact has a metallic support (1) assembled in a precompressed contact chip (2). The contact chip includes a contact layer (8) with conducting agent made of silver whose weight percentage is between 92 to 99 percent of total mass, nickel whose weight percentage is between 0 to 3 percent and carbon whose weight percentage is between 0.5 to 5 percent. A reactive sub-layer (9) includes silver and copper based pseudo-alloy mixed with phosphorus based stripper agent, where fusion temperature of the sub-layer is lower than that of the contact layer. The contact layer includes a fraction of refractory particles such as tungsten carbide particles, tungsten particles and titanium nitride particles, an anti-soldering element such as nickel particles or graphite particles, or gas-producer elements such as carbon fibers. An independent claim is also included for a method for assembling a precompressed contact chip on a metallic support by direct sintering.

IPC 8 full level

**H01H 1/023** (2006.01)

CPC (source: EP)

**H01H 1/0231** (2013.01); **H01H 1/027** (2013.01)

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DOCDB simple family (publication)

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